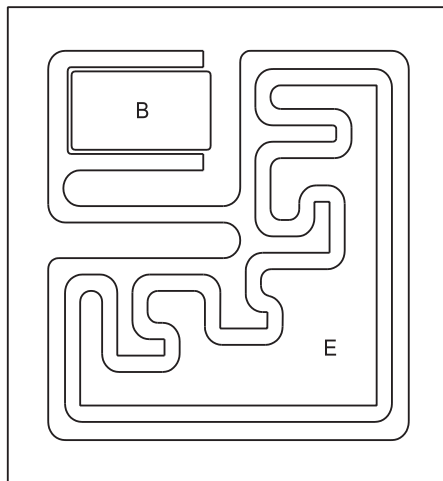


**PROCESS DETAILS**

|                          |                |
|--------------------------|----------------|
| Die Size                 | 131 x 131 MILS |
| Die Thickness            | 12.5 ±1.0 MILS |
| Emitter Bonding Pad Area | 27 x 36 MILS   |
| Base Bonding Pad Area    | 20 x 37 MILS   |
| Top Side Metalization    | Al - 50,000Å   |
| Back Side Metalization   | Ag - 10,000Å   |

**GEOMETRY**



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BACKSIDE COLLECTOR

**PRINCIPAL DEVICE TYPES**

2N6059

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